

ABSTRACT

A dicing die-bonding integrated film and a method for producing the same are disclosed. This dicing die-bonding integrated film includes a base material layer; an adhesive layer formed from an active energy ray-curable adhesive, the adhesive layer having a first surface facing the base material layer and a second surface on the opposite side of the first surface; and a bonding adhesive layer provided so as to cover a central part of the second surface. The active energy ray-curable adhesive includes a (meth)acrylic resin having a functional group capable of chain polymerization, the functional group is at least one selected from an acryloyl group and a methacryloyl group, and the content of the functional group in the (meth)acrylic resin is 0.4 mmol/g or more.

Fig. 1